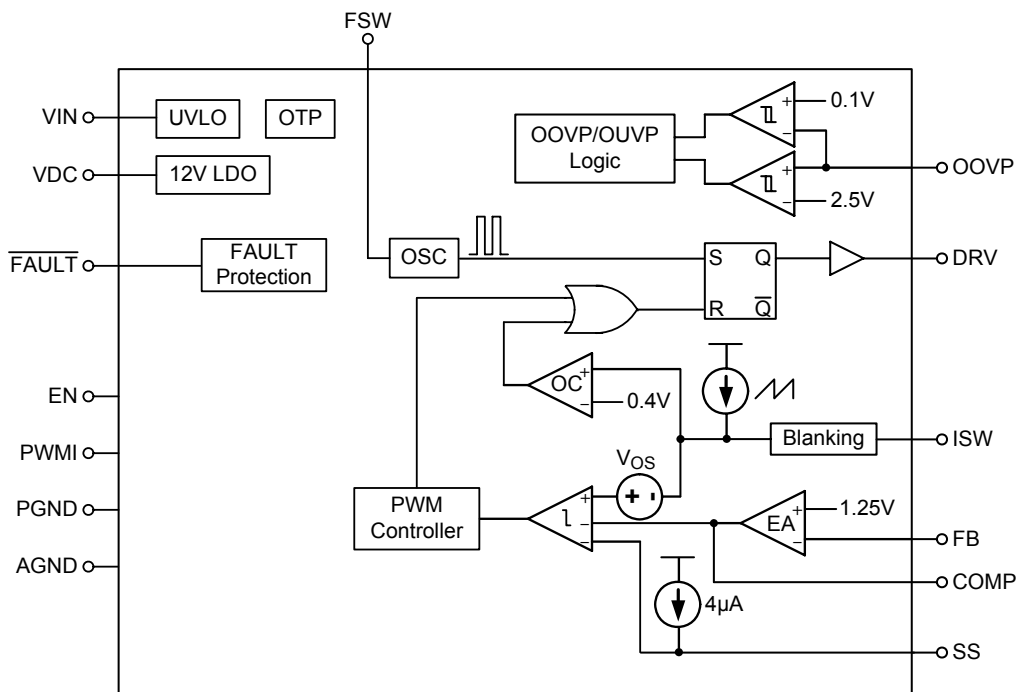


Functional Pin Description

Pin No.	Pin Name	Pin Function
1	VDC	Output of Internal Pre-Regulator.
2	VIN	IC Power Supply.
3	COMP	Compensation for Error Amplifier. Connect a compensation network to ground.
4	SS	External Capacitor to Adjust Soft-Start Time.
5	FSW	Frequency Adjust Pin. This pin allows setting the switching frequency with a resistor from 50kHz to 600kHz.
6	AGND	Analog Ground.
7	PWMI	External Digital Input for Dimming Function.
8	$\overline{\text{FAULT}}$	Open Drain Output for Fault Detection.
9	FB	Feedback to Error Amplifier Input.
10	OOVP	Sense Output Voltage for Over Voltage Protection and Under Voltage Protection.
11	ISW	External MOSFET Switch Current Sense Pin. Connect the current sense resistor between the external N-MOSFET switch and ground.
12	EN	Chip Enable (Active High).
13	PGND	Power Ground of Boost Controller.
14	DRV	Drive Output for the N-MOSFET.

Function Block Diagram



**Absolute Maximum Ratings** (Note 1)

- VIN to GND ----- -0.3V to 32V
- VDC, DRV, FAULT to GND ----- -0.3V to 13.2V
- EN, COMP, SS, FSW, FB, OOV, ISW, PWMI to GND ----- -0.3V to 6V
- Power Dissipation, PD @ TA = 25°C
  - SOP-14 ----- 1.000W
- Package Thermal Resistance (Note 2)
  - SOP-14, θJA ----- 100°C/W
- Lead Temperature (Soldering, 10 sec.) ----- 260°C
- Junction Temperature ----- 150°C
- Storage Temperature Range ----- -65°C to 150°C
- ESD Susceptibility (Note 3)
  - HBM ----- 2kV
  - MM ----- 200V

**Recommended Operating Conditions** (Note 4)

- Supply Input Voltage, VIN ----- 4.5V to 29V
- Junction Temperature Range ----- -40°C to 125°C
- Ambient Temperature Range ----- -40°C to 85°C

**Electrical Characteristics**

(VIN = 21V, VOUT = 50V, TA = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
<b>Input Power Supply</b>							
Quiescent Current	I <sub>Q</sub>	No Switching, R <sub>SW</sub> = 56kΩ	--	1.3	2	mA	
Shutdown Current	I <sub>SHDN</sub>	V <sub>EN</sub> = 0V	--	10	--	μA	
Under Voltage Lockout Threshold	V <sub>UVLO</sub>	V <sub>IN</sub> Rising	--	3.8	--	V	
Under Voltage Lockout Hysteresis	ΔV <sub>UVLO</sub>		--	500	--	mV	
<b>12V Regulator</b>							
Regulator Output Voltage	V <sub>DC</sub>	13.5V < V <sub>IN</sub> < 16V, 1mA < I <sub>LOAD</sub> < 100mA	11.4	12	12.6	V	
		16V < V <sub>IN</sub> < 20V, 1mA < I <sub>LOAD</sub> < 50mA					
		20V < V <sub>IN</sub> < 29V, 1mA < I <sub>LOAD</sub> < 20mA					
Dropout Voltage	V <sub>DROP</sub>	V <sub>IN</sub> - V <sub>DC</sub> , V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 100mA	--	500	--	mV	
Short-Circuit Current Limit	I <sub>SC</sub>	V <sub>DC</sub> Short to GND	--	270	--	mA	
<b>Control Input</b>							
EN Threshold Voltage	Logic-High	V <sub>IH</sub>	2	--	--	V	
	Logic-Low	V <sub>IL</sub>	--	--	0.8		
EN Sink Current	I <sub>IH</sub>	V <sub>EN</sub> = 5V	--	5	--	μA	
Shutdown Delay	Sleeping Mode	t <sub>SLEEP</sub>	R <sub>SW</sub> = 56kΩ, EN = L, 12V Regular Shutdown		55	--	ms
	Shutdown Mode	t <sub>SHDN</sub>	R <sub>SW</sub> = 56kΩ, EN = L, IC Shutdown		110	--	ms

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Boost Controller</b>						
Switching Frequency	$f_{SW}$	$R_{SW} = 56k\Omega$	--	200	--	kHz
Minimum On-Time	$t_{MON}$		--	250	--	ns
Maximum Duty	$D_{MAX}$	Switching	90	--	--	%
Feedback Voltage	$V_{FB}$		1.225	1.25	1.275	V
<b>Slope Compensation</b>						
Peak Magnitude of Slope Compensation Current	$I_{SLOPE, PK}$		--	50	--	$\mu A$
<b>Soft-Start</b>						
Soft-Start Current	$I_{SS}$		3	4	5	$\mu A$
<b>Gate Driver</b>						
DRV On-Resistance	$R_{DS(ON)_N}$	$I_{SINK} = 100mA$ (N-MOSFET)	--	1	--	$\Omega$
	$R_{DS(ON)_P}$	$I_{SOURCE} = 100mA$ (P-MOSFET)	--	1.5	--	$\Omega$
Peak Sink Current	$I_{PEAKsk}$	$C_{LOAD} = 1nF$	--	2.2	--	A
Peak Source Current	$I_{PEAKsr}$	$C_{LOAD} = 1nF$	--	2.55	--	A
Rise Time	$t_r$	$C_{LOAD} = 1nF$	--	6	--	ns
Fall Time	$t_f$	$C_{LOAD} = 1nF$	--	5	--	ns
<b>PWM Dimming Control</b>						
PWMI Threshold Voltage	Logic-High	$V_{PWMI\_H}$	2	--	--	V
	Logic-Low	$V_{PWMI\_L}$	--	--	0.8	
<b>Protection Function</b>						
OCP Threshold	$V_{OCP}$	Including Slope Compensation Magnitude	--	0.4	--	V
$V_{OUT}$ OVP Threshold	$V_{OVP}$		2.375	2.5	2.625	V
$V_{OUT}$ UVP Threshold	$V_{UVP}$		--	0.1	--	V
Thermal Shutdown Temperature	$T_{SD}$		--	150	--	$^{\circ}C$
Thermal Shutdown Hysteresis	$\Delta T_{SD}$		--	50	--	$^{\circ}C$

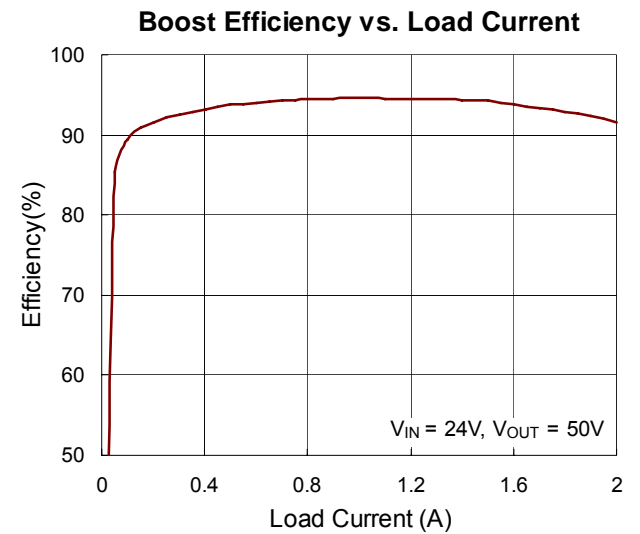
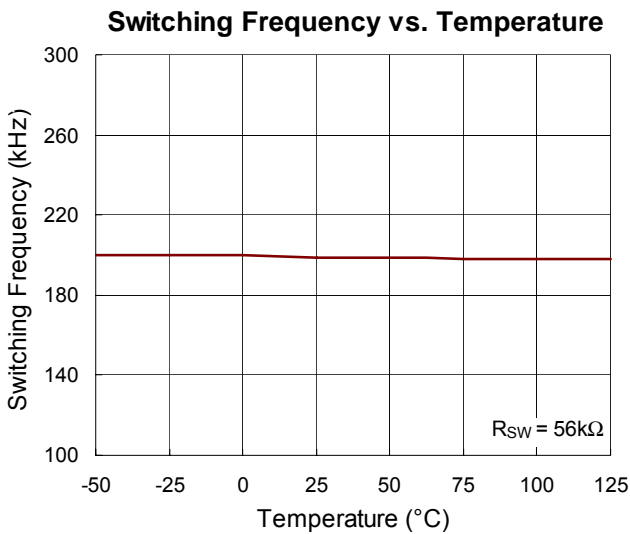
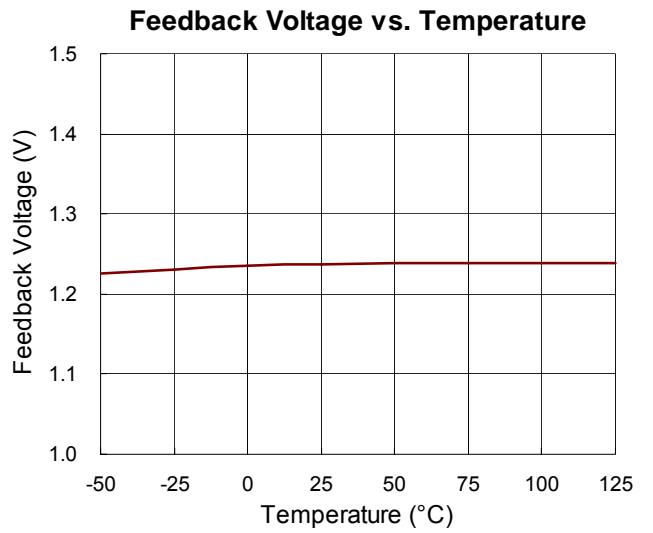
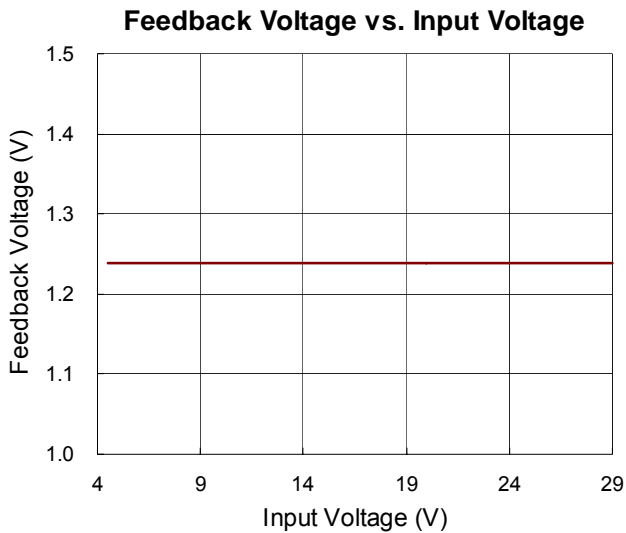
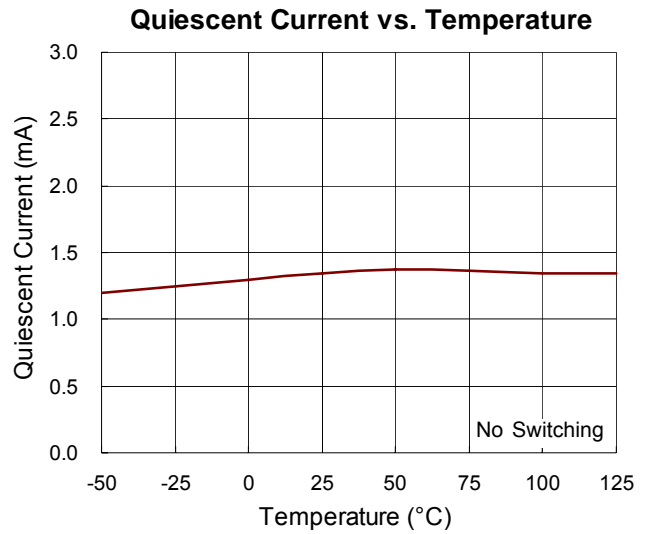
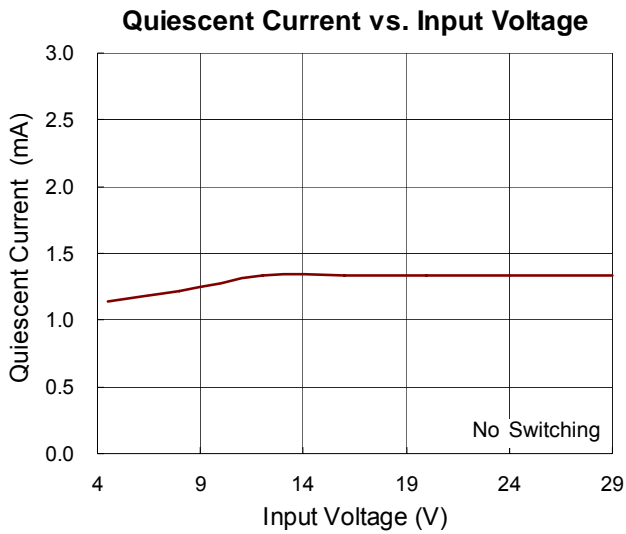
**Note 1.** Stresses beyond those listed "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Note 2.**  $\theta_{JA}$  is measured at  $T_A = 25^{\circ}C$  on a low effective thermal conductivity single-layer test board per JEDEC 51-3.

**Note 3.** Devices are ESD sensitive. Handling precaution is recommended.

**Note 4.** The device is not guaranteed to function outside its operating conditions..

**Typical Operating Characteristics**



## Applications Information

The RT8525 is a wide input operating voltage range step up controller. High voltage output and large output current are feasible by using an external N-MOSFET. The protection functions include output over voltage, output under voltage, over temperature and current limiting protection.

### Boost Output Voltage Setting

The regulated output voltage is set by an external resistor divider according to the following equation :

$$V_{OUT} = V_{FB} \times \left(1 + \frac{R_{FB1}}{R_{FB2}}\right), \text{ where } V_{FB} = 1.25V \text{ (typ.)}$$

The recommended value of  $R_{FB2}$  should be at least 1kΩ for saving sacrificing. Moreover, placing the resistor divider as close as possible to the chip can reduce noise sensitivity.

### Boost Switching Frequency

The RT8525 boost driver switching frequency is able to be adjusted by a resistor  $R_{SW}$  ranging from 18kΩ to 220kΩ. The following figure illustrates the corresponding switching frequency within the resistor range.

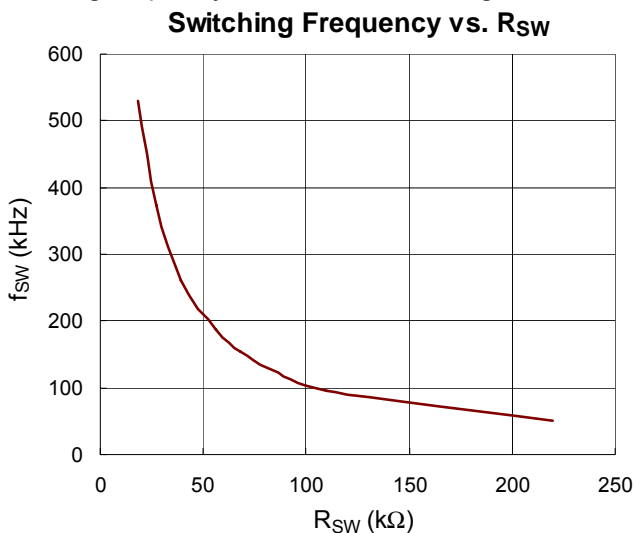


Figure 1. Boost Switching Frequency

### Boost Loop Compensation

The voltage feedback loop can be compensated by an external compensation network consisted of  $R_C$ ,  $C_{C1}$  and  $C_{C2}$ . Choose  $R_C$  to set high frequency gain for fast transient response. Select  $C_{C1}$  and  $C_{C2}$  to set the zero and pole to maintain loop stability. For typical application,

$V_{IN} = 24V$ ,  $V_{OUT} = 50V$ ,  $C_{OUT} = 100\mu F \times 2$ ,  $L1 = 33\mu H$ , while the recommended value for compensation is as follows :  $R_C = 33k\Omega$ ,  $C_{C1} = 27nF$ .

### Soft-Start

The soft-start of the RT8525 can be achieved by connecting a capacitor from the SS pin to GND. The built-in soft-start circuit reduces the start-up current spike and output voltage overshoot. The external capacitor charged by an internal 4μA constant charging current determines the soft-start time. The SS pin limits the rising rate of the COMP pin voltage and thereby limits the peak switch current. The soft-start interval is set by the soft-start capacitor according to the following equation :

$$t_{SS} \cong C_{SS} \times 5 \times 10^5$$

A typical value for the soft-start capacitor is 0.33μF. The soft-start capacitor is discharged when EN voltage falls below its threshold after shutdown delay or UVLO occurs.

### Slope Compensation and Current Limiting

A slope compensation is applied to avoid sub-harmonic oscillation in current-mode control. The slope compensation voltage is generated by the internal ramp current flow through a slope compensation resistor  $R_{SLP}$ . The inductor current is sensed by the sensing resistor  $R_S$ . Both of them are added and presented on the ISW pin. The internal ramp current is rising linearly from zero at the beginning of each switching cycle to 50μA in maximum on-time of each cycle. The slope compensation resistor  $R_{SLP}$  can be calculated by the following equation :

$$R_{SLP} > \frac{(V_{OUT} - V_{IN}) \times R_S}{2 \times L \times 50\mu \times f_{sw}}$$

where  $R_S$  is current sensing resistor,  $L$  is inductor value, and  $f_{sw}$  is boost switching frequency.

The current flow through inductor during charging period is detected by a sensing resistor  $R_S$ . Besides, the slope compensation voltage also attributes magnitude to ISW. As the voltage at the ISW pin is over 0.4V, the DRV will be pulled low and turn off the external N-MOSFET. So that the inductor will be forced to leave charging stage and enter discharging stage to prevent over current. The current limiting can be calculated by the following equation:

$$R_S < \frac{0.4 - D_{MAX} \times R_{SLP} \times 50\mu}{I_{L, PK}}$$

where  $I_{L, PK}$  is peak inductor current, and  $D_{MAX}$  is maximum duty.

**Output Over Voltage Protection**

The output voltage can be clamped at the voltage level determined by the following equation :

$$V_{OUT (OOVP)} = V_{OOVP} \times \left(1 + \frac{R_{OVP1}}{R_{OVP2}}\right),$$

where  $V_{OOVP} = 2.5V$  (typ.)

where  $R_{OVP1}$  and  $R_{OVP2}$  are the voltage divider connected to the OOVP pin.

**Fault Protection**

The  $\overline{FAULT}$  pin will be pulled low once a protection is triggered, and a suitable pulled-high  $R_{FLT}$  is required. The suggested  $R_{FLT}$  is 100kΩ if the pulled-high voltage was 12V. The following figure illustrates the fault protection function block. If one of the OUVP and OTP occurs, the switch 1 will be turned on, and the voltage at node A will

be under 0.25V. Then the protection function will perform action 2 to turn off the driver. When protection function is released, the RT8525 will re-start.

On the other hand, if the triggered protection is OOVP, the voltage at node A will be decided by voltage divider composed of  $R_{FLT}$  and the internal 8kΩ resistor. This voltage must be designed between 0.25V and 1.25V by choosing  $R_{FLT}$  appropriately. Once the OOVP turns on the Switch 2, the divided  $\overline{FAULT}$  voltage will activate action 1 to turn off the driver without resetting soft-start. Therefore, when protection function OOVP is released, the RT8525 will be in normal operation.

**Power MOSFET Selection**

For the applications operating at high output voltage, switching losses dominate the overall power loss. Therefore, the power N-MOSFET switch is typically chosen for drain voltage, VDS, rating and low gate charge. Consideration of switch on-resistance  $R_{DS(ON)}$  is usually secondary. The VDC regulator in the RT8525 has a fixed output current limit to protect the IC and provide 12V DRV voltage for N-MOSFET switch gate driver.

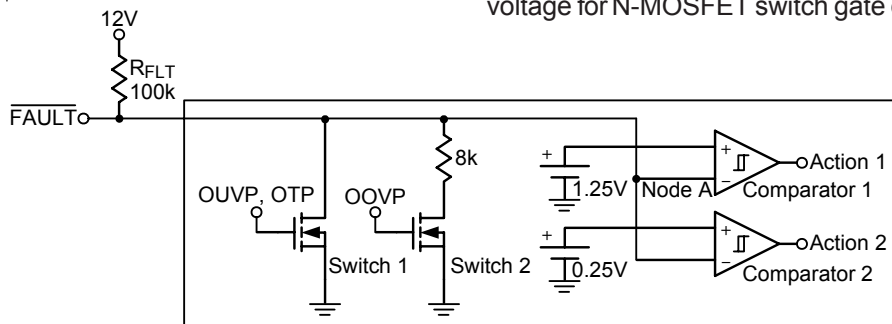


Figure 2. Fault Protection Function Block

**Inductor Selection**

The boundary value of the inductance L between Discontinuous Conduction Mode (DCM) and Continuous Conduction Mode (CCM) can be approximated by the following equation :

$$L = \frac{D \times (1-D)^2 \times V_{OUT}}{2 \times f_{sw} \times I_{OUT}}$$

where

$V_{OUT}$  is the maximum output voltage,

$V_{IN}$  is the minimum input voltage,

$f_{sw}$  is the operating frequency,

$I_{OUT}$  is the sum of current from all LED strings,

and D is the duty cycle calculated by the following equation :

$$D = \frac{V_{OUT} - V_{IN}}{V_{OUT}}$$

The boost converter operates in DCM over the entire input voltage range if the inductor value is less than the boundary value L. With an inductance greater than L, the converter operates in CCM at the minimum input voltage and may transit to DCM at higher voltages. The inductor must be

selected with a saturated current rating greater than the peak current provided by the following equation :

$$I_{LPK} = \frac{V_{OUT} \times I_{OUT}}{\eta \times V_{IN}} + \frac{V_{IN} \times D \times T}{2 \times L}$$

where  $\eta$  is the efficiency of the power converter.

### Diode Selection

Schottky diodes are recommended for most applications because of their fast recovery time and low forward voltage. The power dissipation, reverse voltage rating and pulsating peak current are the important parameters for Schottky diode selection. Make sure that the diode's peak current rating exceeds  $I_{LPK}$ , and reverse voltage rating exceeds the maximum output voltage.

### Capacitor Selection

Output ripple voltage is an important index for estimating the performance. This portion consists of two parts, one is the product of input current and ESR of output capacitor, another part is formed by charging and discharging process of output capacitor. Refer to figure 3, evaluate  $\Delta V_{OUT1}$  by ideal energy equalization. According to the definition of Q, the Q value can be calculated as following equation :

$$Q = \frac{1}{2} \times \left[ \left( I_{IN} + \frac{1}{2} \Delta I_L - I_{OUT} \right) + \left( I_{IN} - \frac{1}{2} \Delta I_L - I_{OUT} \right) \right] \times \frac{V_{IN}}{V_{OUT}}$$

$$\times \frac{1}{f_{SW}} = C_{OUT} \times \Delta V_{OUT1}$$

where  $f_{SW}$  is the switching frequency, and  $\Delta I_L$  is the inductor ripple current. Move  $C_{OUT}$  to the left side to estimate the value of  $\Delta V_{OUT1}$  as the following equation :

$$\Delta V_{OUT1} = \frac{D \times I_{OUT}}{\eta \times C_{OUT} \times f_{SW}}$$

Finally, by taking ESR into consideration, the overall output ripple voltage can be determined as the following equation :

$$\Delta V_{OUT} = I_{IN} \times ESR + \frac{D \times I_{OUT}}{\eta \times C_{OUT} \times f_{SW}}$$

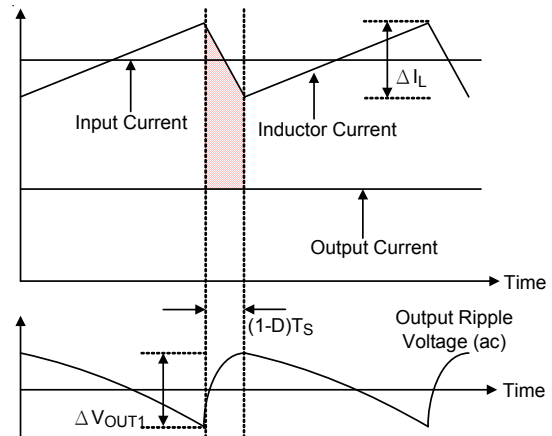


Figure 3. The Output Ripple Voltage without the Contribution of ESR

### Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance,  $\theta_{JA}$ , is layout dependent. For SOP-14 packages, the thermal resistance,  $\theta_{JA}$ , is 100°C/W on a standard JEDEC 51-3 single-layer thermal test board. The maximum power dissipation at  $T_A = 25^\circ\text{C}$  can be calculated by the following formula :

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (100^\circ\text{C}/\text{W}) = 1.000\text{W for SOP-14 package}$$

The maximum power dissipation depends on the operating ambient temperature for fixed  $T_{J(MAX)}$  and thermal resistance,  $\theta_{JA}$ . The derating curve in Figure 4 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.



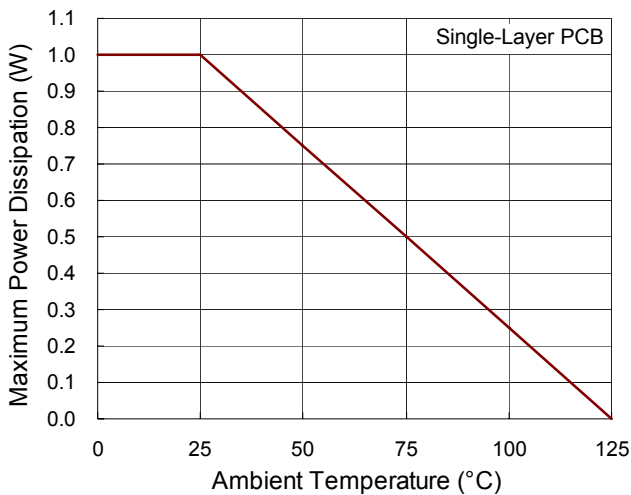


Figure 4. Derating Curve of Maximum Power Dissipation

**Layout Considerations**

PCB layout is very important for designing switching power converter circuits. The following layout guides should be strictly followed for best performance of the RT8525.

- ▶ The power components  $L_1$ ,  $D_1$ ,  $C_{IN}$ ,  $C_{OUT}$ ,  $M_1$  and  $R_s$  must be placed as close as possible to reduce current loop. The PCB trace between power components must be as short and wide as possible.
- ▶ Place components  $R_{FB1}$ ,  $R_{FB2}$ ,  $R_{OVP1}$  and  $R_{OVP2}$  close to IC as possible. The trace should be kept away from the power loops and shielded with a ground trace to prevent any noise coupling.
- ▶ The compensation circuit should be kept away from the power loops and should be shielded with a ground trace to prevent any noise coupling. Place the compensation components to the COMP pin as close as possible, no matter the compensation is  $R_C$ ,  $C_{C1}$  or  $C_{C2}$ .

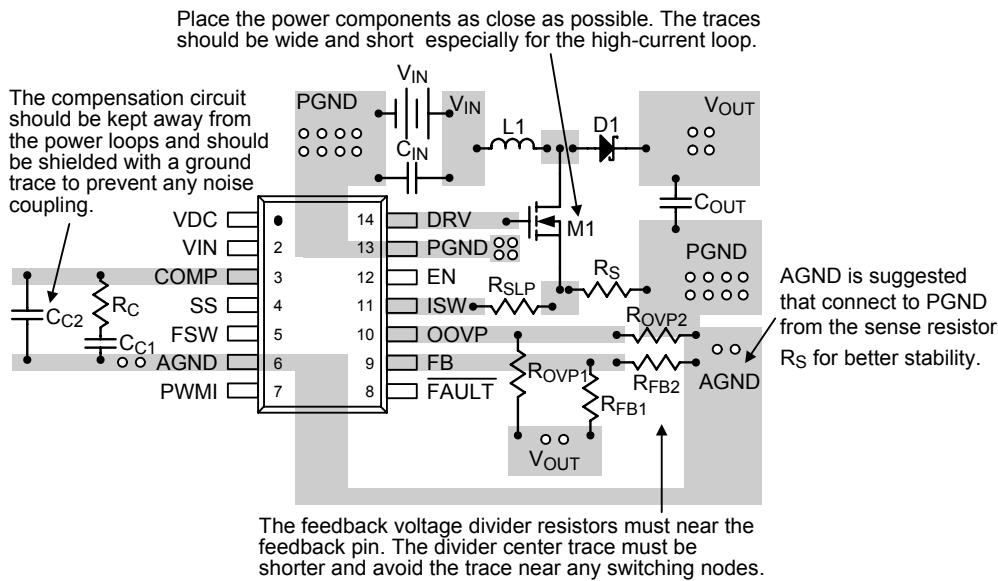
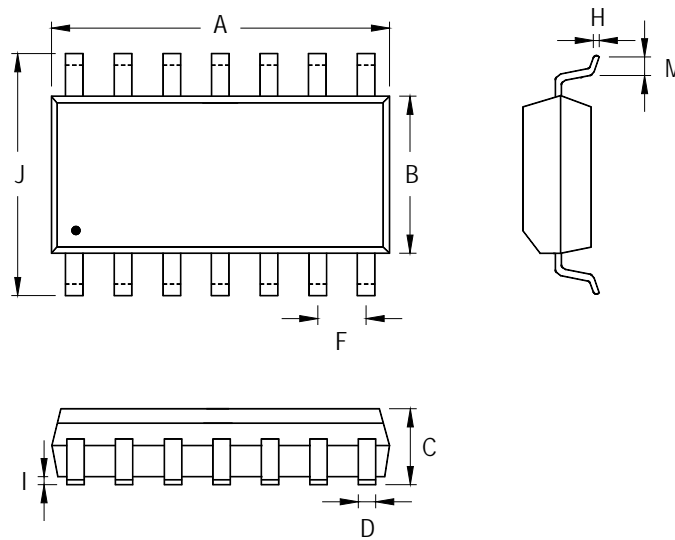


Figure 5. PCB Layout Guide



Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	8.534	8.738	0.336	0.344
B	3.810	3.988	0.150	0.157
C	1.346	1.753	0.053	0.069
D	0.330	0.508	0.013	0.020
F	1.194	1.346	0.047	0.053
H	0.178	0.254	0.007	0.010
I	0.102	0.254	0.004	0.010
J	5.791	6.198	0.228	0.244
M	0.406	1.270	0.016	0.050

14-Lead SOP Plastic Package

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